

*Amendments to the Claims*

1. (currently amended) A multiple layer inductor implemented on a substrate having a plurality of surfaces layers, each layer having a top surface and a bottom surface, said multiple layer inductor comprising:

a first spiral conductive pattern disposed on a top surface of a first of the plurality of surfaces layers;

a second spiral conductive pattern disposed on a top surface of a second of the plurality of surfaces layers;

a continuing interconnection coupled to said first and second spiral conductive patterns;

an interface having a first terminal and a second terminal disposed on said top surface of said first of the plurality of layers, wherein said first terminal is coupled to said first and second spiral conductive patterns and second terminal is coupled to said second spiral conductive pattern; and

a first conductive shield pattern having a first common voltage potential and disposed on a top surface of a third of the plurality of surfaces layers, wherein said third of the plurality of layers surface is adjacent to said second of the plurality of layers surface; and

a second conductive shield pattern having a second common voltage potential and disposed on a top surface of a fourth of the plurality of layers, wherein said fourth of the plurality of layers is adjacent to said top surface of said first of the plurality of layers.

2. (cancelled)

3. (currently amended) The multiple layer inductor of claim 1, wherein said continuing interconnection comprises:

a first via coupled to said first and second spiral conductive patterns; and

a second via coupled to said second spiral conductive pattern and said second terminal interface.

4 - 7. (withdrawn)

8. (original) The multiple layer inductor of claim 1, wherein said first and second spiral conductive patterns have different orientations.

9. (canceled)

10. (original) The multiple layer inductor of claim 9, wherein said first and second shield patterns are grounded.

11-21. (withdrawn)